

# Development of the Global IC Packaging and Testing Industry, 2019 and Beyond

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## Abstracts

Worldwide OSAT (Outsourced Semiconductor Assembly and Test) companies who perform IC packaging and testing services registered significant shipment value growth in 2018, thanks to a continued increase in memory production and an advanced inventory replenishment in anticipation of potential tariff increases from the US-China trade war. Worldwide IC packaging and testing industry shipment value in 2018 totaled US\$29.462 billion in 2018, up by 7.69% compared to 2017. This report reviews the performance of the worldwide IC packaging and testing industry in 2018 and analyzes its development in 2019 and beyond.

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